



**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-24. (canceled)

25. (currently amended) A method of mounting electrical component assemblies on opposite sides of a printed circuit card, said printed circuit card being provided with a plurality of through holes and having connection pads on a both sides, comprising:

inserting a chock on a first side of the printed circuit card, said chock having a thickness about equal to a thickness of one of [[the]]two electrical component assemblies to be mounted on said printed circuit card and said chock having a plurality of through holes that correspond to the plurality of through holes in said printed circuit card;

inserting a standoff through each through hole in said printed circuit card and said chock and placing a spring around each standoff to be used to press said chock against said printed circuit card;

pressing the chock against the printed circuit card;  
mounting a first electrical component assembly on a second side of the printed circuit card;

placing a package tool having a plurality of springs on a horizontal support; so that when

placing the first mounted electrical component assembly is placed inside the package tool so that the springs of the package tool come into contact with the first electrical component assembly;

removing the chock from the first side of said printed circuit card such that springs of the package tool exert a force that compensates for the weight of the first electrical component assembly inside the package tool; and

mounting a second electrical component assembly on the first side of the printed circuit card.

26. (previously presented) The method of claim 25, wherein the first and second electrical component assemblies are integrated circuits.

27. (previously presented) The method of claim 25, wherein said chock is pressed against the printed circuit card through screws in the standoffs.

28. (previously presented) The method of claim 25, wherein said mounting a first electrical component assembly comprises:

placing an insert having electrical contacts on the printed circuit card so that electrical contacts of the insert coincide with electrical contacts of the second side of the printed circuit card;

placing an electrical component having pins on the insert so the pins of the component coincide with electrical contacts of the insert;

placing a plate on the electrical component and the insert;

placing a heat sink on the plate, electrical component and insert; and

exerting pressure on the heat sink, plate, electrical component and insert to mount the assembly comprising the heat sink, plate, electrical component and insert to the printed circuit card.

29. (canceled)